

# TI Precision Designs: Verified Design 0.1Hz to 10Hz Noise Filter



## TI Precision Designs

TI Precision Designs are analog solutions created by TI's analog experts. Verified Designs offer the theory, component selection, simulation, complete PCB schematic & layout, bill of materials, and measured performance of useful circuits. Circuit modifications that help to meet alternate design goals are also discussed.

## Design Resources

[Design Archive](#)  
[TINA-TI™](#)  
[OPA827](#)

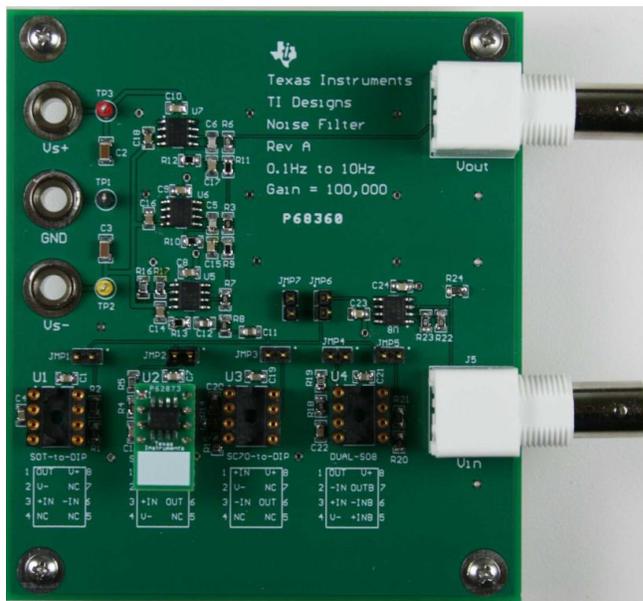
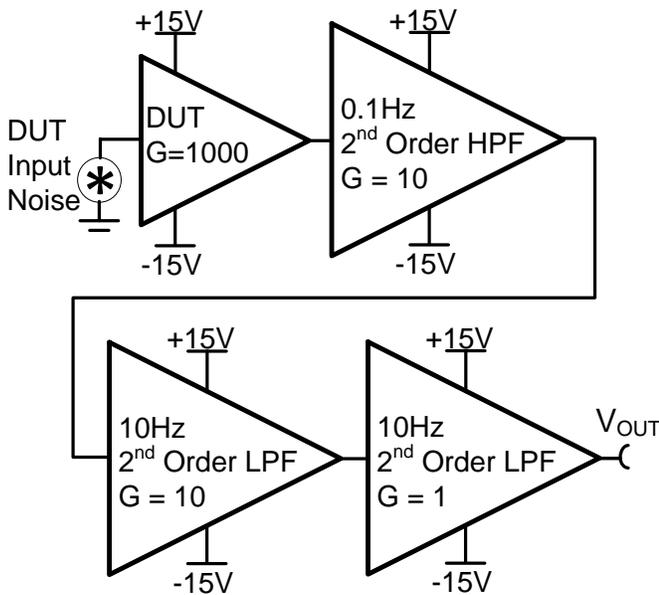
All Design files  
SPICE Simulator  
Product Folder

## Circuit Description

This circuit is designed to amplify low frequency noise (0.1Hz to 10Hz) to a level that is easily measured by an oscilloscope. It achieves this function with a 0.1Hz, second order, high pass filter and a 10Hz, fourth order, low pass filter. The 0.1Hz to 10Hz noise measurement is a common figure of merit given in amplifier data sheets. This design is intended to facilitate the measurement 0.1Hz to 10Hz noise for the commonly used different op amp package styles.



[Ask The Analog Experts](#)  
[WEBENCH® Design Center](#)  
[TI Precision Designs Library](#)



**An IMPORTANT NOTICE at the end of this TI reference design addresses authorized use, intellectual property matters and other important disclaimers and information.**

TINA-TI is a trademark of Texas Instruments  
WEBENCH is a registered trademark of Texas Instruments

## 1 Design Summary

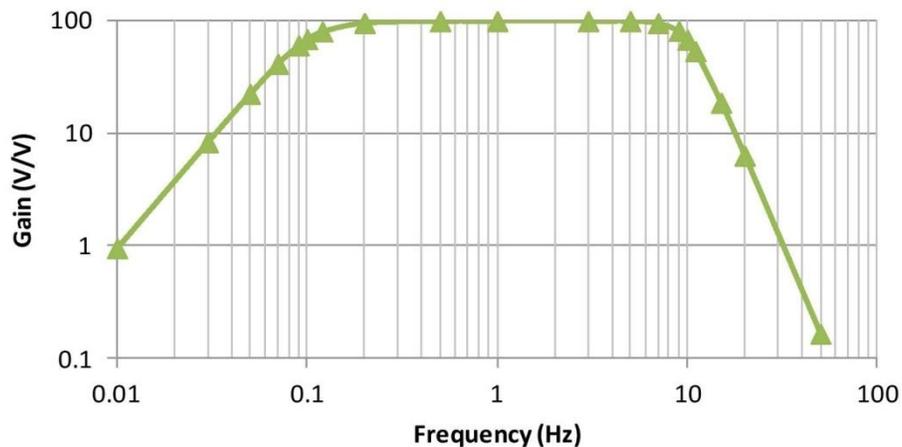
The design requirements are as follows:

- Supply Voltage: +/-15 V dc, or +/-2.5V dc
- Input: noise (nV) – exact magnitude depends on amplifier
- Output: noise (mV) – Large enough to read on scope
- Total Gain: 100dB, 100,000V/V
- Filter Gain: 40dB, 100V/V

The design goals and performance are summarized in Table 1. Figure 1 depicts the design's measured filter response.

**Table 1: Measured and simulated performance of filter**

	Ideal	Nominal simulation	Simulated Monte Carlo Low	Simulated Monte Carlo High	Measured
Amplitude at 0.1Hz (V/V)	70.07	70.98	59.56	77.05	67.9
Amplitude at 10Hz (V/V)	70.07	70.06	61.56	76.57	67.5
Amplitude at 1Hz (V/V)	100	99.68	96	100.68	98.75



**Figure 1: Measured Filter Response**

## 2 Theory of Operation

The objective of this circuit is to amplify low frequency noise to a level that can be measured by a typical oscilloscope. This measurement is a common figure of merit given in amplifier data sheets. The standard bandwidth used in these measurements is 0.1Hz to 10Hz. Many precision amplifiers will have a total noise on the order of 100nVp-p referred to input (RTI). The gain of this circuit is set to make the signal delivered to the oscilloscope input in the 10mVpp or greater. Note that many oscilloscopes have a 1mV/division range when using a direct BNC connection. The Device Under Test (DUT) is in high gain so that it is the dominant noise source and the noise in the filter stages is not significant. The goal of the filter stages is to have low noise, accurate filter cut-off frequencies, and accurate gain.

Low frequency noise specifications are always referred to the input of the DUT. In the example shown in Figure 2 the noise measured by the oscilloscope is 10mVpp. The noise RTI is calculated by dividing the output noise by the total gain. In this example the total gain is 100,000 (100 x 1,000), so the noise RTI can be calculated by dividing the output by the total gain ( $V_n\text{-RTI} = 10\text{mV} / 100,000 = 100\text{nVpp}$ ).

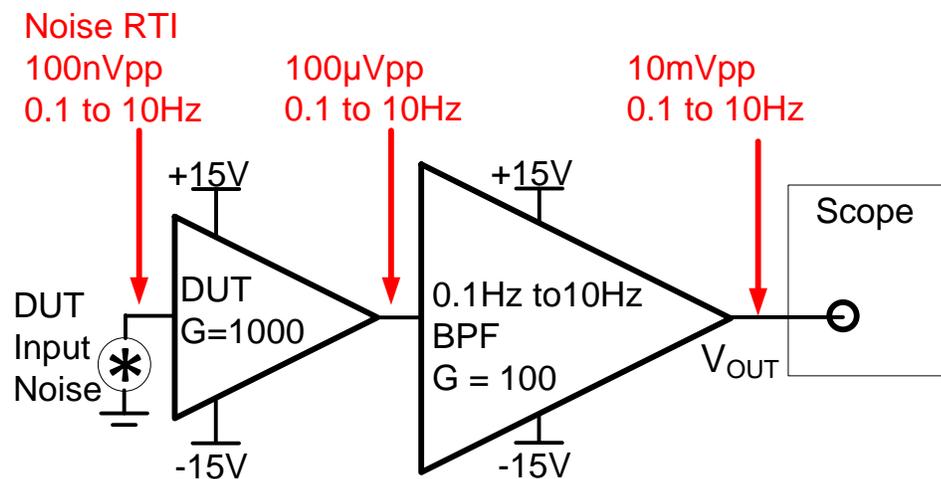


Figure 2: Simplified block diagram

## 2.1 Detailed Schematic

A more complete schematic for this design is shown in Figure 3. The first stage is the Device Under Test (DUT). This device is socketed to allow the easy testing of different devices. The three stages following the DUT form a 0.1Hz (second order) to 10Hz (fourth order) band pass filter. The objective is to amplify the low frequency voltage noise on the OPA827 to a level that can easily be read by an oscilloscope. The bandwidth choice of 0.1Hz to 10Hz is an industry standard.

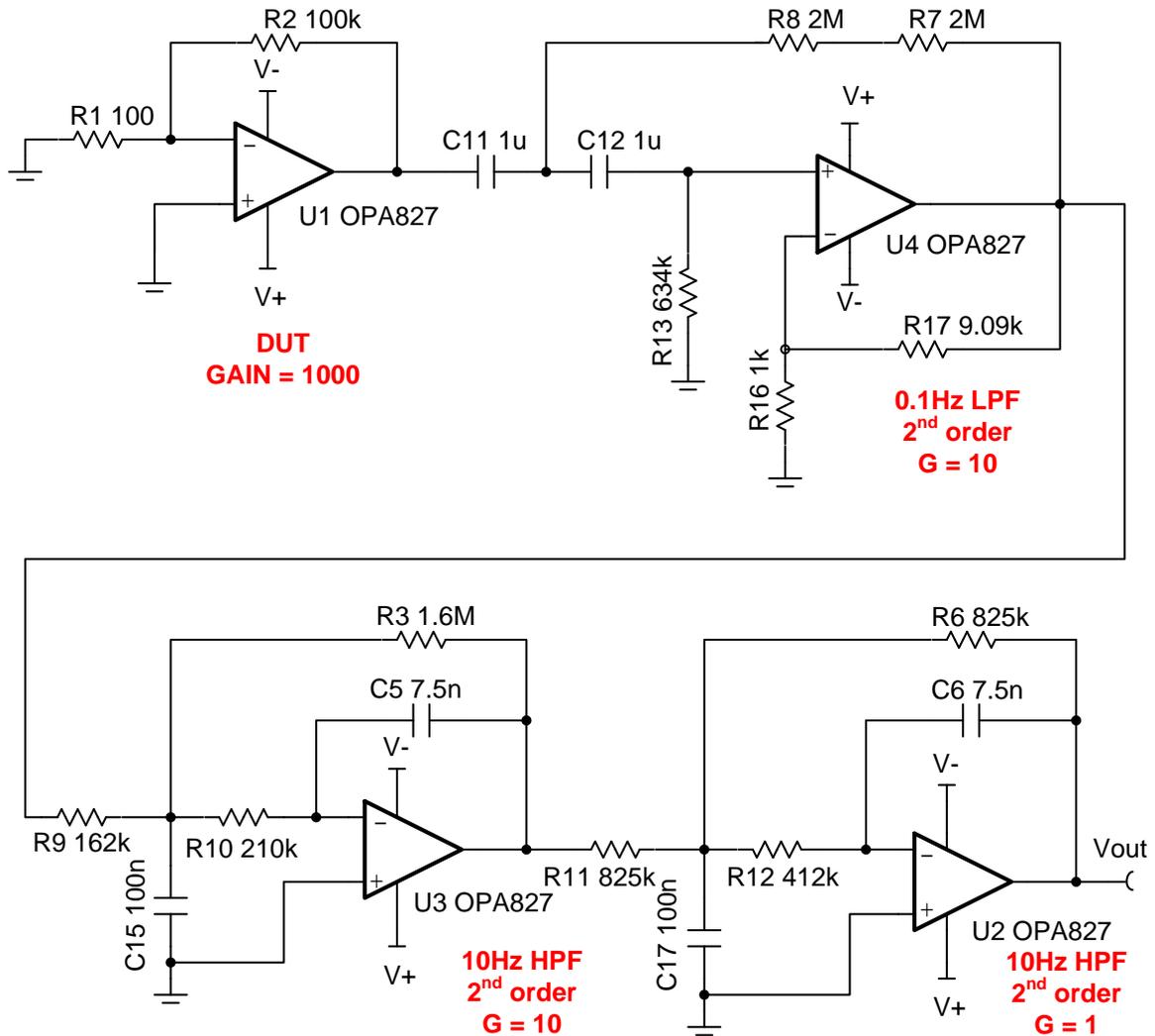


Figure 3 Complete Circuit Schematic

## 2.2 1st Stage - DUT

The purpose of this circuit is to measure the low frequency noise of op amps. The first stage is the op amp that we want to test and is referred to as the Device Under Test (DUT). As shown in Figure 4, the DUT is in high gain (1000x) to insure that its noise is dominant and the noise in subsequent stages is not significant. The parallel combination of the gain setting resistors is selected to minimize their thermal noise ( $R_{eq} = 100\text{ k}\Omega \parallel 100\text{ }\Omega = 99.9\text{ }\Omega$ ). Figure 5 shows the relationship between resistance and thermal noise. In this circuit the noise generated by the equivalent resistance is about 1.1nV for  $R_{eq}=99.9\text{ }\Omega$ .

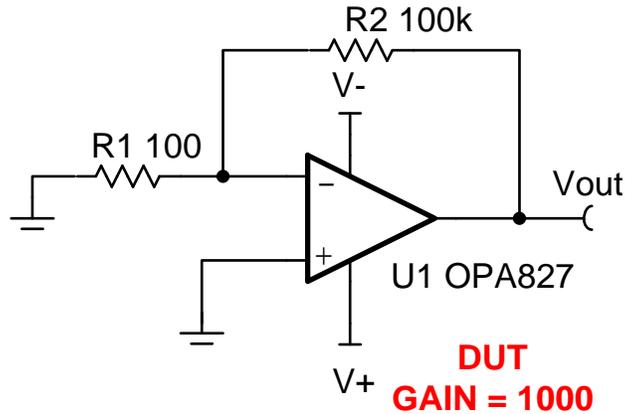


Figure 4: First Stage – Device under test in gain of 1000 to amplify noise

### Noise Spectral Density vs. Resistance

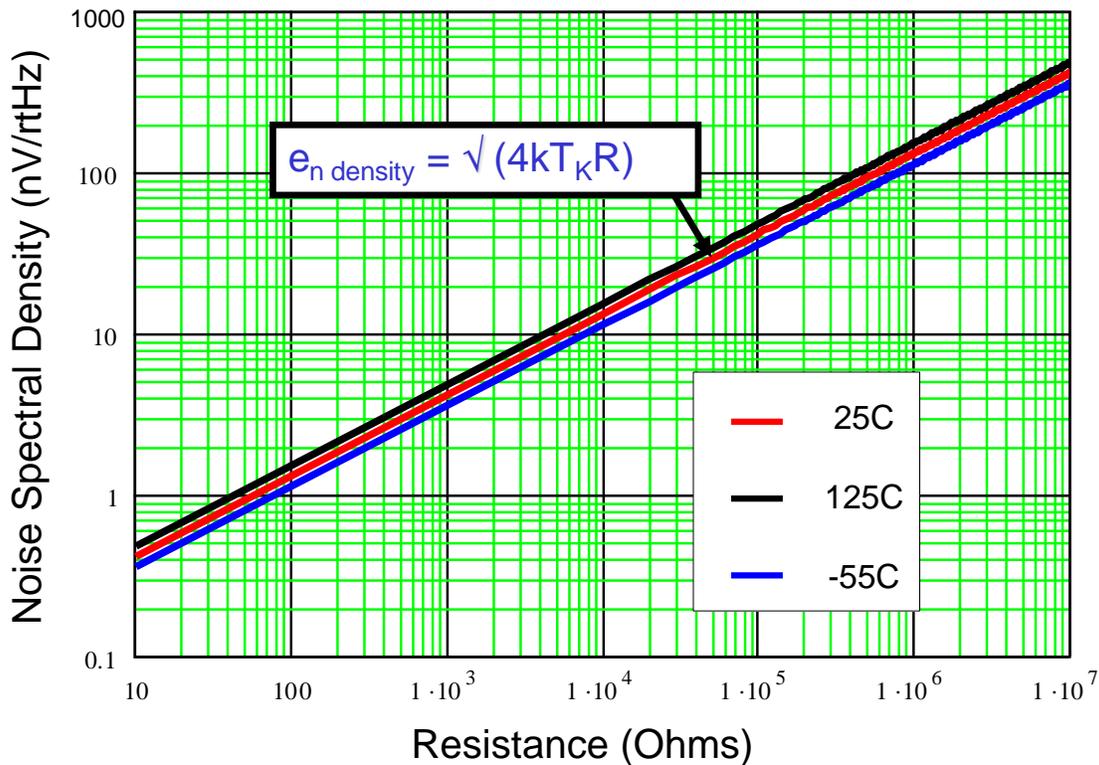
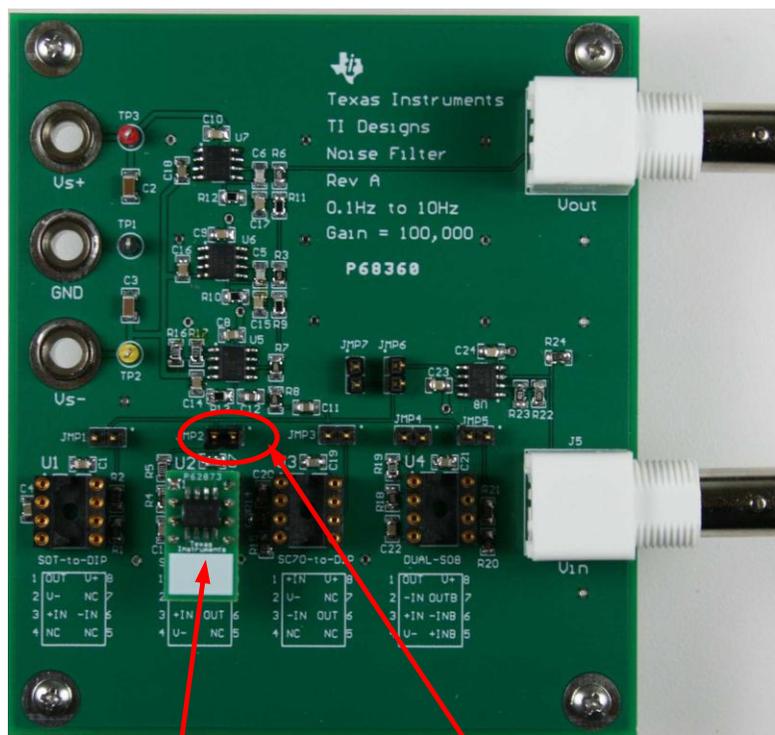


Figure 5: Noise spectral density vs. input resistor.

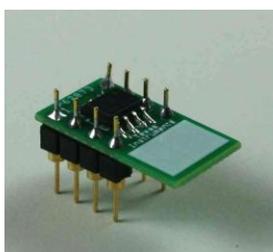
The first stage uses DIP sockets to allow easy interchangeability of the DUT. The first stage has four different sockets that are configured for the DIP adaptor card for common packages (i.e. SOT, SO8, SC70, and DUAL-SO8). The PCB silk screen below the dip socket shows the pin configuration for each socket. Figure 6 shows the PCB with a DIP adaptor installed in socket U2. The jumper JMP2 is used to select the output of U2. Figure 7 shows the DIP adaptor card. The gerber files for the DIP adaptor cards are included in the TI-Design folder. Also, all the common DIP adaptor cards are included in the DIP-ADAPTOR-EVM.



DIP Sockets allow the installation of different types of amplifiers. The devices are soldered to DIP adaptor cards.

Jumpers allow the selection of the different sockets.

**Figure 6: First stage uses socketed DIP adaptor cards and jumper selection**



**Figure 7: DIP adaptor board**

Figure 8 shows how the different package configurations in the first stage are jumper selected. It is important that the jumper is connected to only one output at a time to prevent connecting two op amp outputs together.

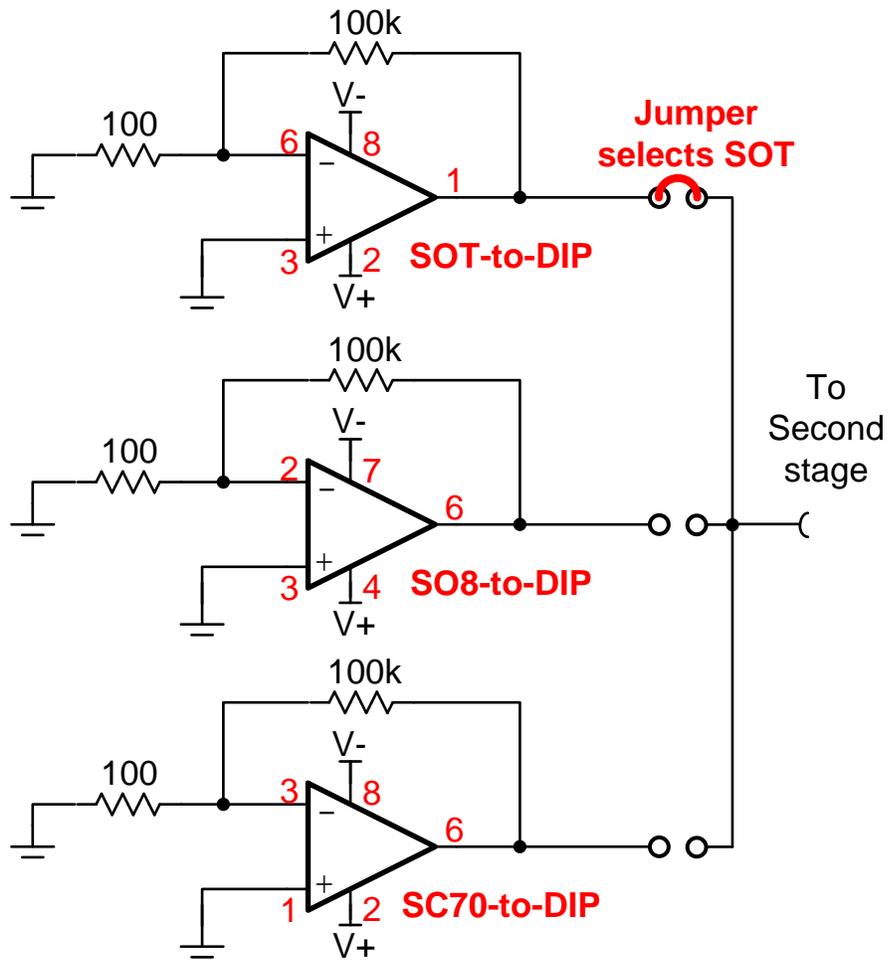


Figure 8: First stage uses jumpers to select different package types

### 2.3 2<sup>ND</sup> Stage 0.1Hz HPF

The second stage is a 0.1Hz high pass filter in a gain of 10 (Figure 9). A Texas Instruments software tool called Filter-pro™ can be used to design the filters in this design. The filter was selected to be a second order Butterworth, Sallen-Key, high pass filter. The Butterworth frequency response was selected to be maximally flat. The Sallen-Key topology is used because it produces more reasonable component values; i.e. the capacitors and resistors are in the range available for low cost precision components.

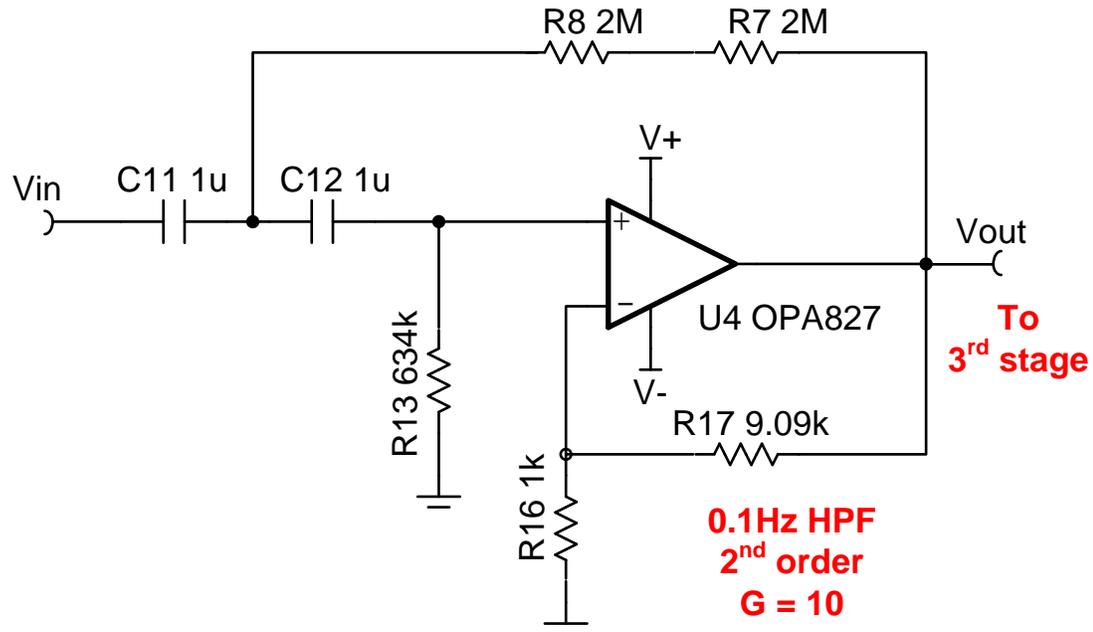


Figure 9: Second Stage – 0.1Hz, 2nd order High Pass Filter, Gain = 10

## 2.4 3<sup>RD</sup> Stage 10Hz LPF

The third stage is a 10Hz low pass filter in a gain of 10 (Figure 9). The filter was selected to be a second order Butterworth Multiple-Feedback high pass filter. The Butterworth frequency response was selected to be maximally flat. The Multiple-Feedback topology is used because it produces more reasonable component values; i.e. the capacitors and resistors are in the range available for low cost precision components.

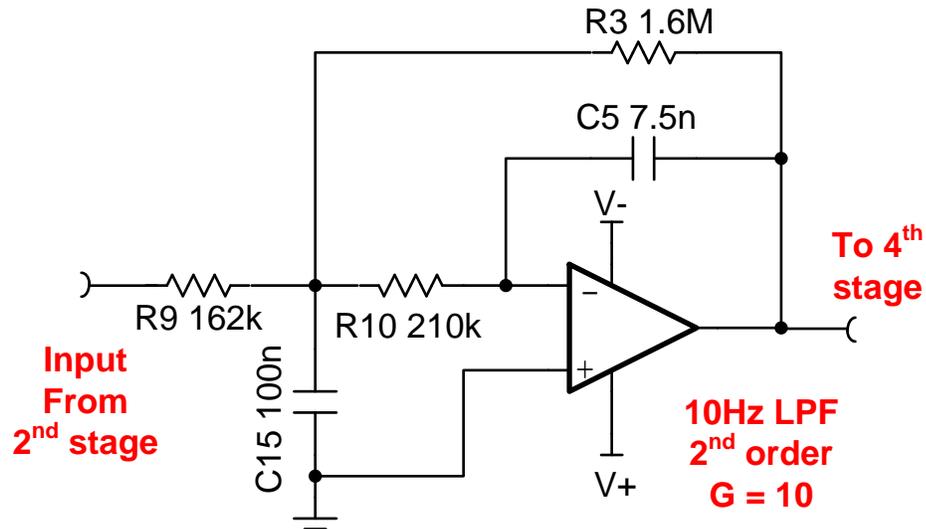


Figure 10: Third Stage – 10Hz, 2nd order Low Pass Filter, Gain = 10

## 2.5 4<sup>th</sup> Stage 10Hz LPF

The fourth stage is a 10Hz low pass filter in a gain of 1 (Figure 11). It is similar to the third stage but with a gain of 1. The objective of the third and fourth stage is to create a 4<sup>th</sup> order low pass filter. The filter was selected to be a second order, Butterworth, Multiple-Feedback, high pass filter. The Butterworth frequency response was selected to be maximally flat. The Multiple-Feedback topology is used because it produces more reasonable component values; i.e. the capacitors and resistors are in the range available for low cost precision components.

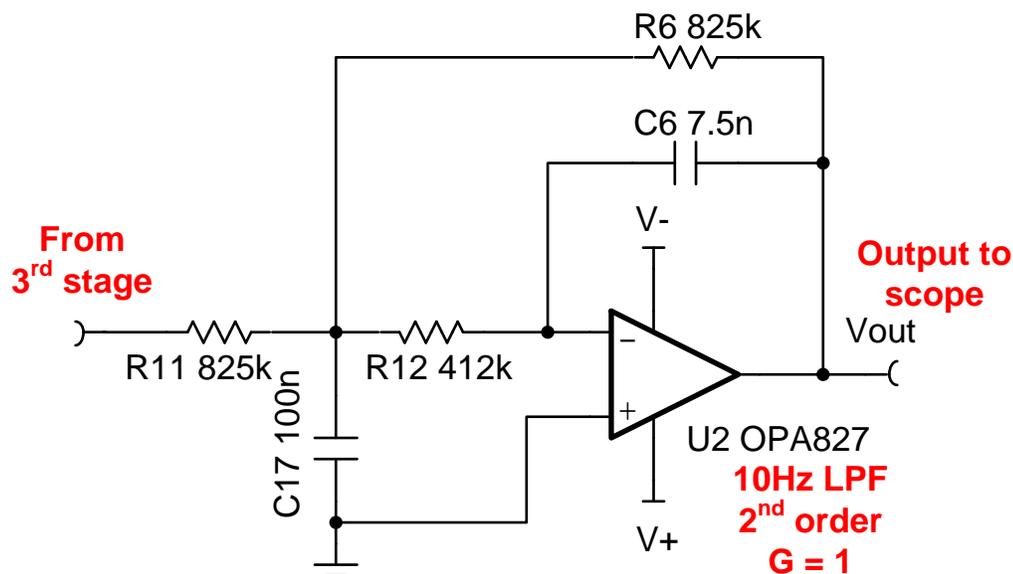


Figure 11: Fourth Stage – 10Hz, 2nd order Low Pass Filter, Gain = 1

## 3 Component Selection

### 3.1 Op Amp Selection

The op amps used in the three stage filter were selected to minimize noise, bias current, and offset drift. The goal is to insure that the filter does not add any noise or drift to the DUT. The reason for using a low drift amplifier is that offset drift and bias current drift can easily be mistaken as noise in the 0.1Hz to 10Hz range. Also note that the impedances involved in the filter are large (i.e. greater than 100k) so low bias current is needed to avoid large offsets and drifts. Because the DUT is in high gain it is not really critical that the amplifiers are ultra high precision; nevertheless, it is recommended using a high precision op amp in case lower DUT gain is used. The OPA827 was used in the filter stages for this design.

### 3.2 Passive Component Selection

It is important for this circuit to have good gain accuracy and accurate cutoff frequencies. The accuracy of the cutoff frequencies is determined by tolerance of the resistors and capacitors in the filters. In general, the tolerance of the capacitors will be the limiting factor. The COG / NPO type chip capacitors have the best accuracy (1% to 5%). These types of capacitors also have the best temperature and voltage coefficients. Unfortunately, these capacitors are only available for smaller capacitance ranges (i.e.  $C < 0.47\mu\text{F}$ ). As an alternative, X7R capacitors with a high voltage rating (i.e. 50V or greater) and a low tolerance (i.e. 5% or better) can be used where large capacitors are required. Note that capacitors with a larger voltage rating will have a smaller voltage coefficient. The resistors are selected with 1% tolerance or better to minimize gain error.

#### 4 Simulation

The TINA-TI™ schematic shown in Figure 12 includes the circuit values obtained in the design process.

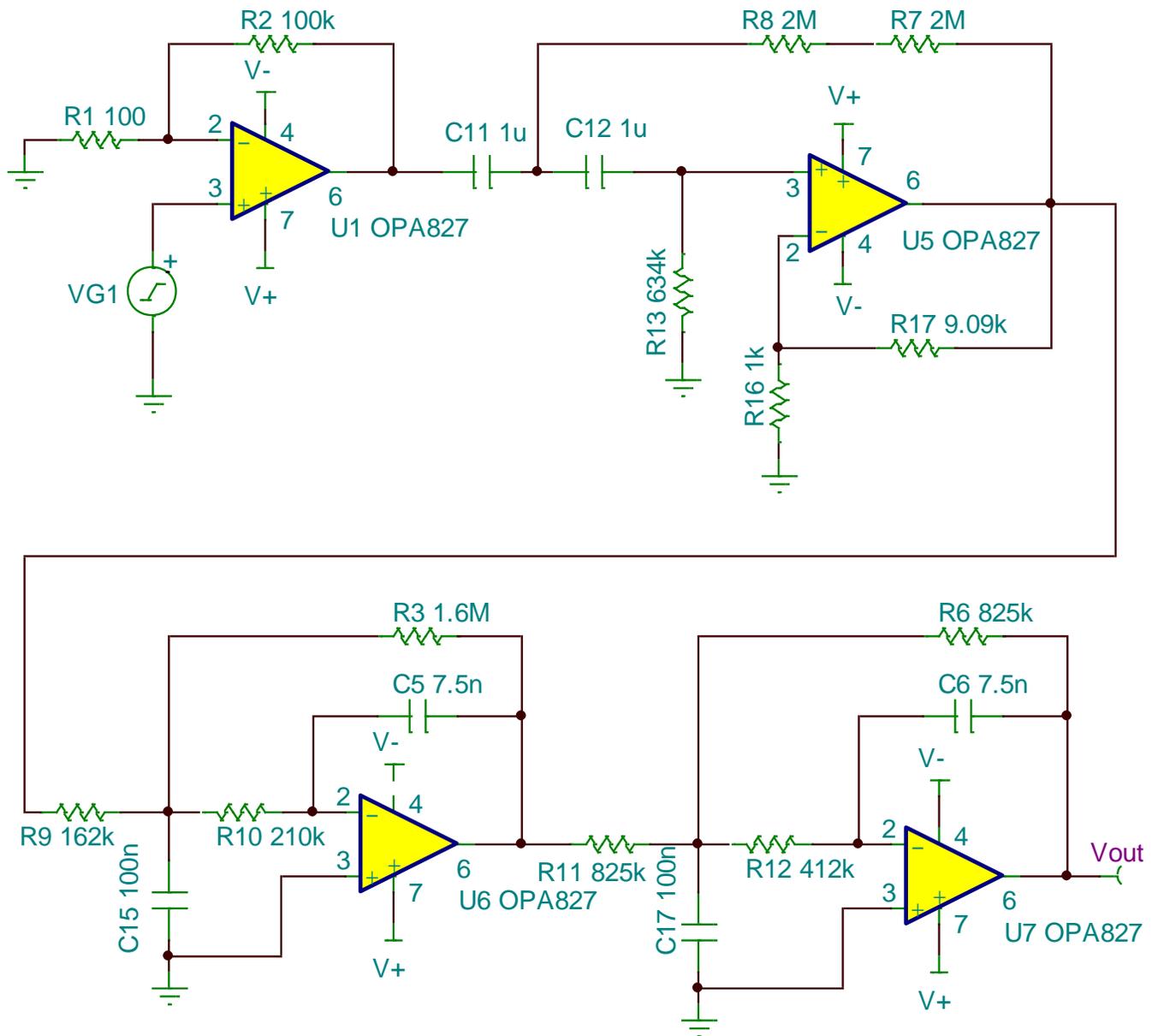


Figure 12: TINA-TI™ Spice Schematic

### 4.1 AC Transfer Function

The simulated dc transfer function of the filter (stages 2, 3, and 4) are shown Figure 13. The results of a Monte-Carlo analysis are shown in Figure 14. The Monte-Carlo analysis uses the resistor and capacitor tolerance to do a statistical analysis that shows the expected variation of the filters transfer function. Table 2 summarizes the results of the Monte-Carlo analysis and compares it to measured results.

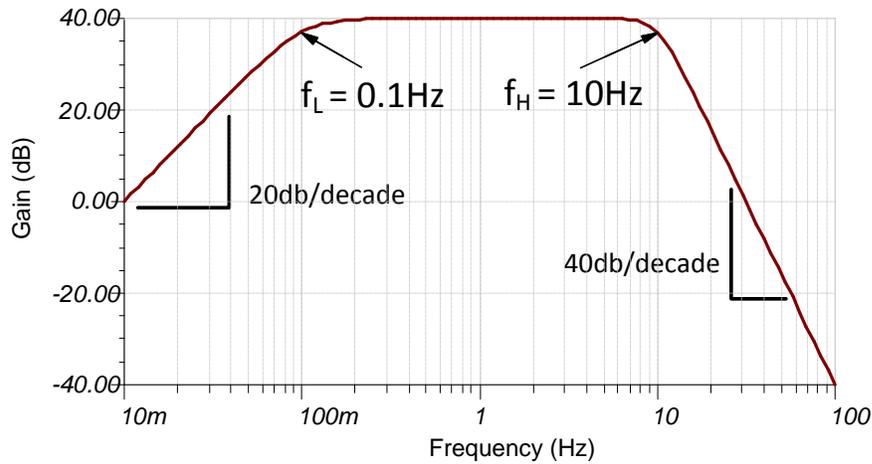


Figure 13: Gain vs. Freq for the filter only (Max Gain = 40dB, or 100x)

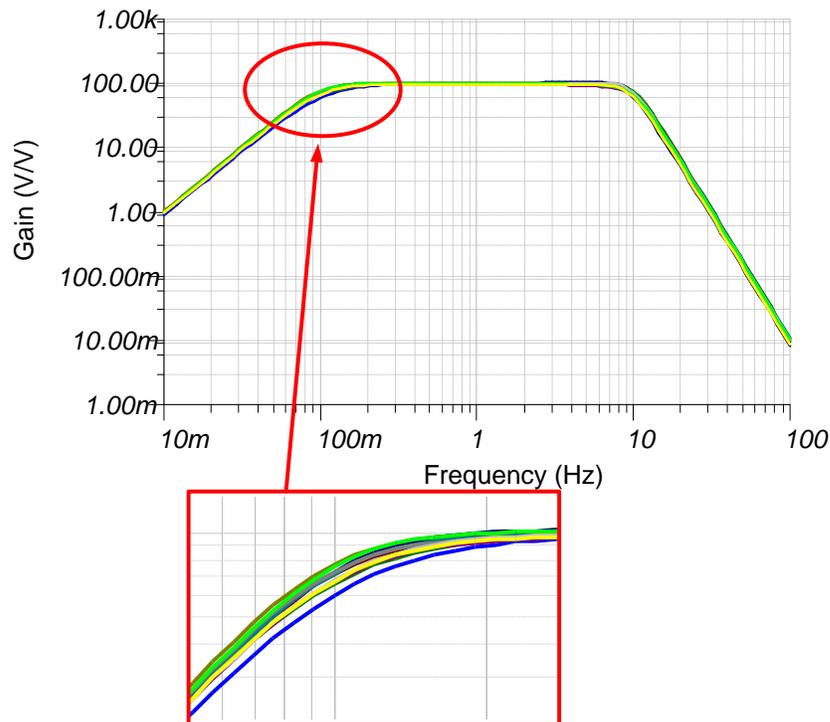


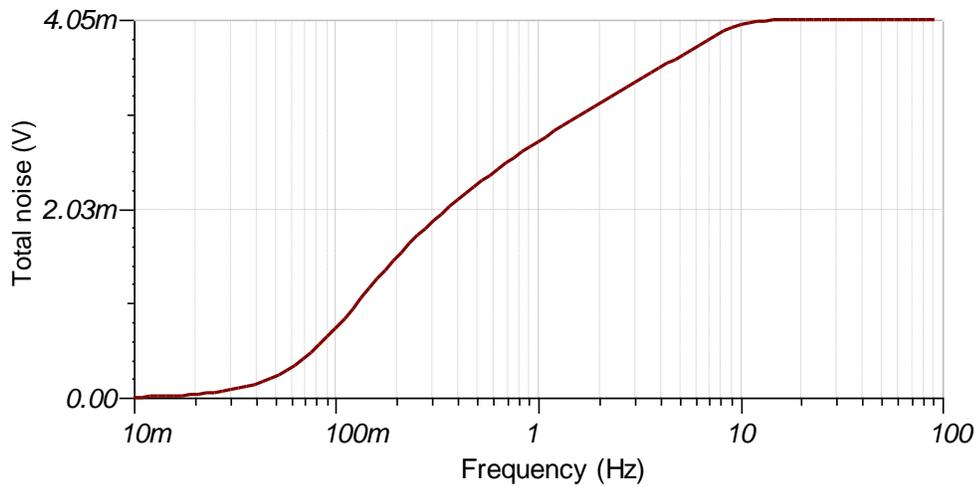
Figure 14: Monte Carlo Analysis of frequency response

**Table 2: Simulated results including statistical variation**

	Ideal	Nominal simulation	Simulated Monte Carlo Low	Simulated Monte Carlo High	Measured
<b>Amplitude at 0.1Hz</b>	70.07	70.98	59.56	77.05	67.9
<b>Amplitude at 10Hz</b>	70.07	70.06	61.56	76.57	67.5
<b>Amplitude at 1Hz</b>	100	99.68	96	100.68	98.75

**4.2 Simulated Noise results**

Figure 15 shows the total integrated noise for the circuit with OPA827 being used as the DUT. This result is the equivalent RMS output noise. To get an estimate of the peak-to-peak noise, multiply this estimate by 6 (see Equation (1)). Figure 16 and Table 3 show the expected variation using the Monte Carlo analysis. The Monte Carlo Analysis will take into account all the variability of the capacitor and resistors tolerance.



**Figure 15: Total Noise where OPA827 is the filter amplifier and the DUT**

$$\begin{aligned}
 V_{out_{pp}} &= 6 * V_{out_{rms}} = 6 * (4.05mV_{rms}) \\
 &= 24.3mV_{pp}
 \end{aligned}
 \tag{1}$$

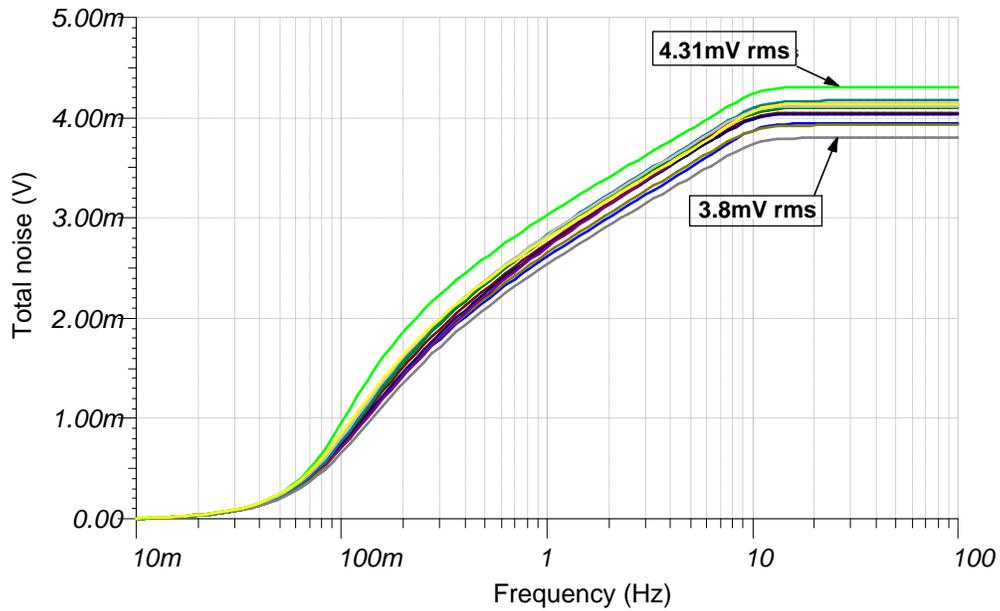


Figure 16: Total noise variability using Monte Carlo Analysis for OPA827

Table 3: Summary of total noise variability using Monte Carlo Analysis

	Data sheet	Nominal simulated	Simulated Monte Carlo Low	Simulated Monte Carlo High	Measured
<b>OPA827 0.1Hz to 10Hz</b>	250nVpp 41.7nV rms	243nVpp 40.5nV rms	228nVpp 38nV rms	258nVpp 43.1nVpp	250nVpp 41.7nV rms

## 5 PCB Design

The PCB schematic and Bill of Materials can be found in Section 8.

### 5.1 PCB Layout

The general guidelines for precision PCB layout were used on this design. For example, trace lengths are kept to minimum length especially input signals.

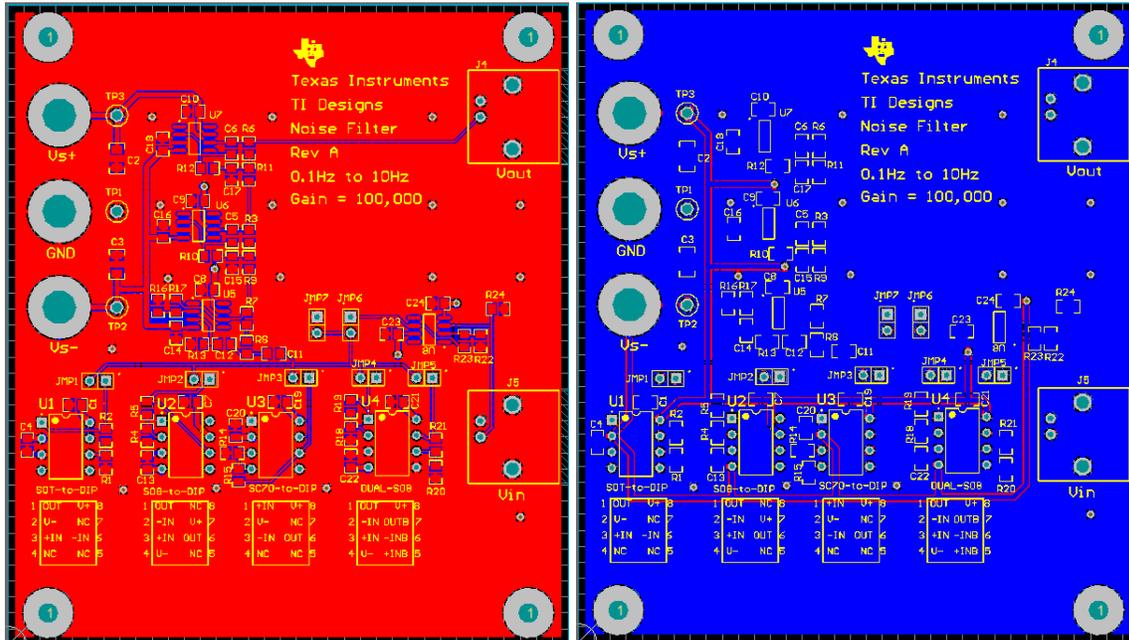


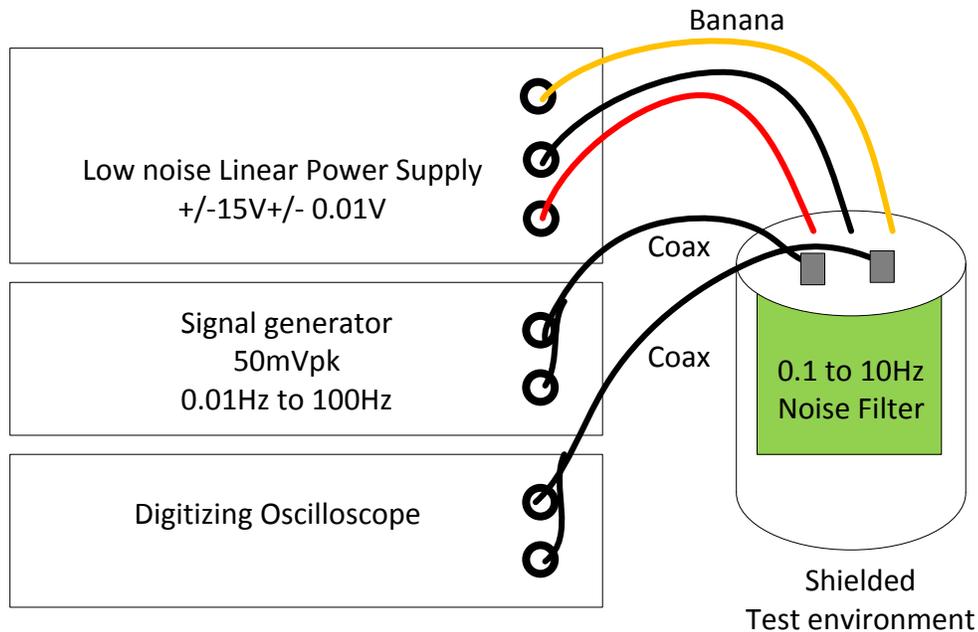
Figure 17: PCB Layout (Top on Left, Bottom on Right)

## 6 Verification & Measured Performance

### 6.1 General precautions used in measuring 0.1Hz to 10Hz noise

Figure 18 shows the test setup to confirm the operation of the 0.1Hz to 10Hz filter. The idea behind this setup is to sweep the frequency of the input and measure the gain vs. frequency response for the filter. This setup is only for initial test and characterization of the board. After initial test, the setup shown in Figure 19 will be used to measure the 0.1Hz to 10Hz noise.

It is important to use a shielded environment to get the best results from this test. Figure 20 shows the one possible option for a shielded environment. This is a steel paint can with BNC and banana connections drilled through the top. This shield is effective at shielding the noise filter from 60Hz and other noise pickup. It also minimizes temperature shifts by protecting the board from air turbulence. It is important that the entire shield is grounded, and minimal air gaps (slot antennas). If a paint can is used, make sure that the lid and can make a good seal. It may be necessary to sand the rim in the lid of the paint can to insure that the lid and can make good electrical contact.



**Figure 18: Test setup for V-to-I board**

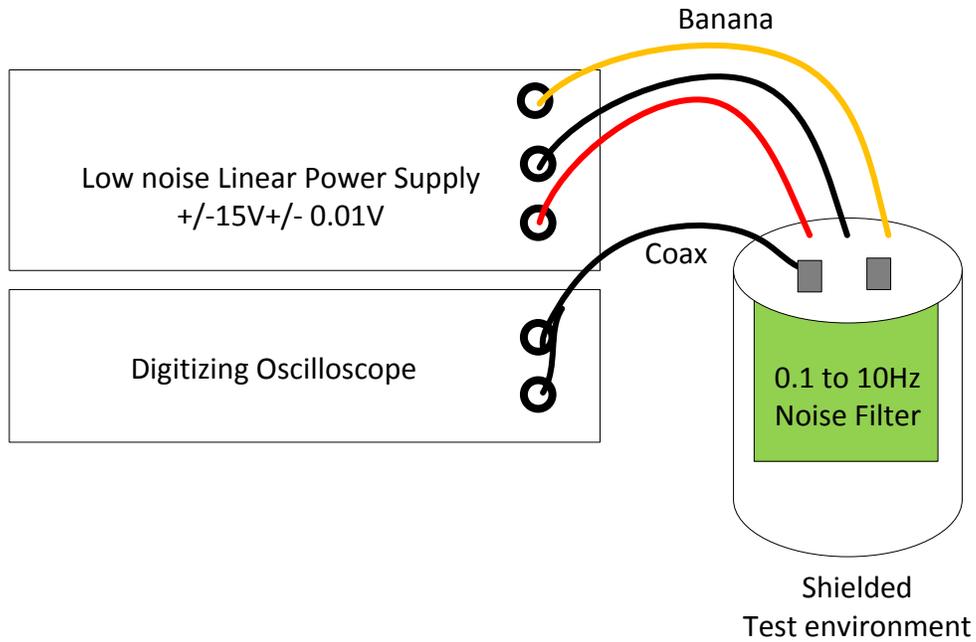


Figure 19: Setup for testing 0.1Hz to 10Hz noise

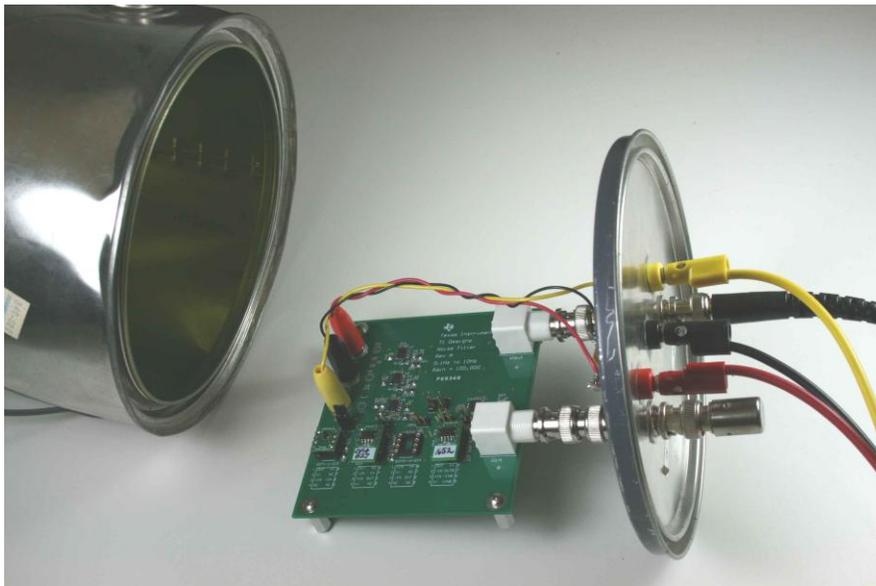


Figure 20: Shielded environment used to measure noise

## 6.2 Transfer Function

Data was collected by sweeping the frequency of  $V_{IN}$  from 0.03Hz to 50Hz while measuring output response. This measurement is made for the filter only ( $V_{in}$  to J5 and  $V_{out}$  to J4 on the PCB). Figure 21 displays the measured results in Volts-per-Volt. The errors measured at specific frequency are summarized in Table 4.

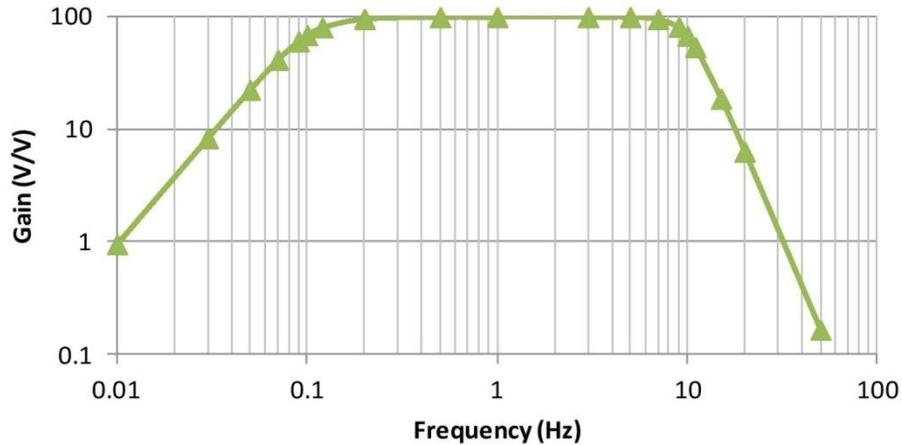


Figure 21: Measured Filter Response

Table 4: Summary of measured errors at key frequencies

	Ideal	Nominal	Simulated Monte Carlo Low	Simulated Monte Carlo High	Measured
Amplitude at 0.1Hz (V/V)	70.07	70.98	59.56	77.05	67.9
Amplitude at 10Hz (V/V)	70.07	70.06	61.56	76.57	67.5
Amplitude at 1Hz (V/V)	100	99.68	96	100.68	98.75

### 6.3 Measured scope output

The goal of this circuit is to produce the 0.1Hz to 10Hz oscilloscope noise measurements that are given in data sheets. Figure 22 shows the 0.1Hz to 10Hz noise measurement for the OPA277 as well as its spectral density. The spectral density curve can be used with a hand calculation to confirm that the 0.1Hz to 10Hz measurement is correct. Equations (2) and (3) show the calculation for the expected noise for an OPA277 with the 0.1Hz to 10Hz filter. Equation (1) normalizes the flicker noise to 1Hz and equation (3) integrates the noise from 0.1Hz to 10Hz. Further details on the derivation and usage of these equations are given in reference 1. In this case the measured result is lower than expected ( $E_{n\text{-meas}} = 150\text{nV}$ ,  $E_{n\text{-calc}} = 218\text{nV}$ ). Equation (4) shows how the scope reading is divided by the gain to obtain the noise RTI.

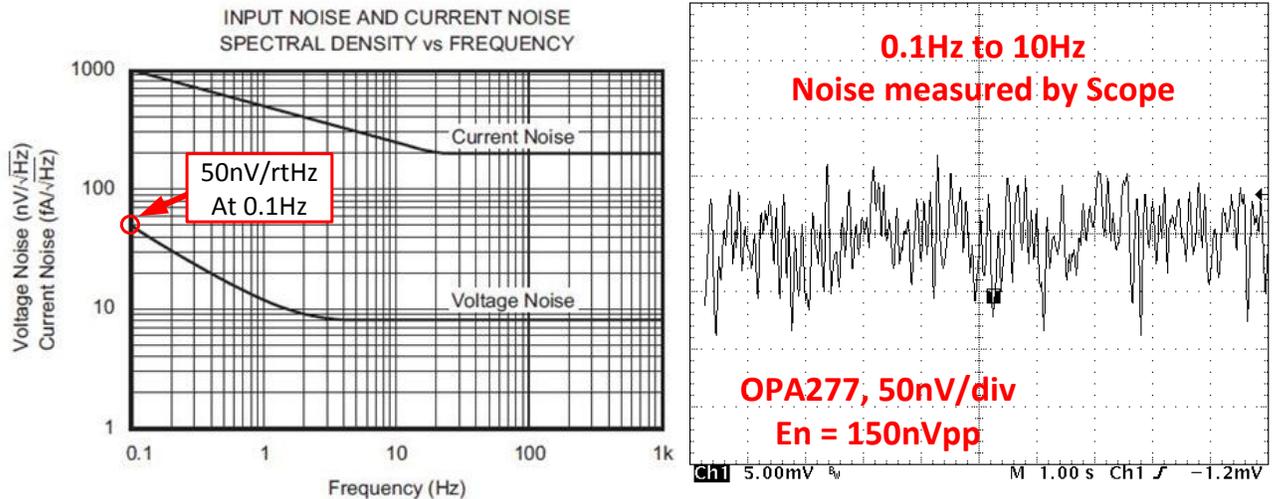


Figure 22: Scope noise output and voltage noise spectral density for OPA277

$$e_{f\text{norm}} = e_{at\_f}\sqrt{f} = (50 \text{ nV}/\sqrt{\text{Hz}})\sqrt{0.1\text{Hz}} = 15.8\text{nV} \quad (2)$$

$$E_{n277\text{-calc}} = 6 * 15.8\text{nV} * \ln\left(\sqrt{\frac{10\text{Hz}}{0.1\text{Hz}}}\right) = 218\text{nVpp} \quad (3)$$

$$E_{n277\text{-meas}} = \frac{V_{\text{Scope-pp}}}{100,000} = \frac{15\text{mVpp}}{100,000} = 150\text{nVpp} \quad (4)$$

Figure 23 is a second example showing how the measured filter output can be predicted using the spectral density curve and hand calculations. Equations (5), and (6) show the hand calculation of the filter output noise. Figure 24 shows two additional measured results but does not show the hand calculations. Equation (7) shows how the scope reading is divided by the gain to obtain the noise RTI.

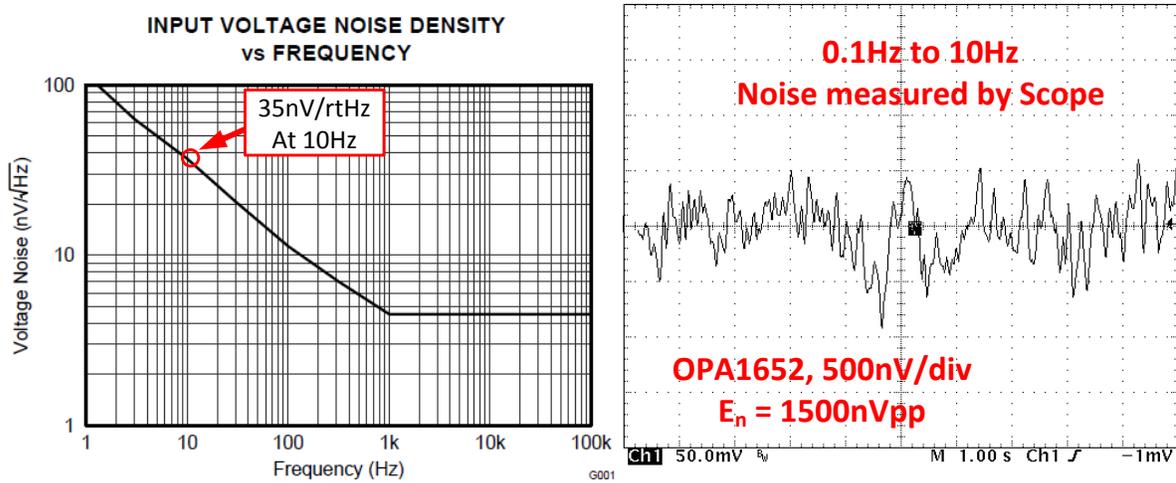


Figure 23: Scope noise output and voltage noise spectral density for OPA1652

$$e_{f\text{norm}} = e_{at\_f} \sqrt{f} = (35 \text{ nV}/\sqrt{\text{Hz}}) \sqrt{10\text{Hz}} = 111\text{nV} \quad (5)$$

$$E_{n1652} = 6 * 111\text{nV} * \ln \left( \frac{10\text{Hz}}{0.1\text{Hz}} \right) = 1530\text{nVpp} \quad (6)$$

$$E_{n1652\text{-meas}} = \frac{V_{\text{Scope-pp}}}{100,000} = \frac{150\text{mVpp}}{100,000} = 1500\text{nVpp} \quad (7)$$

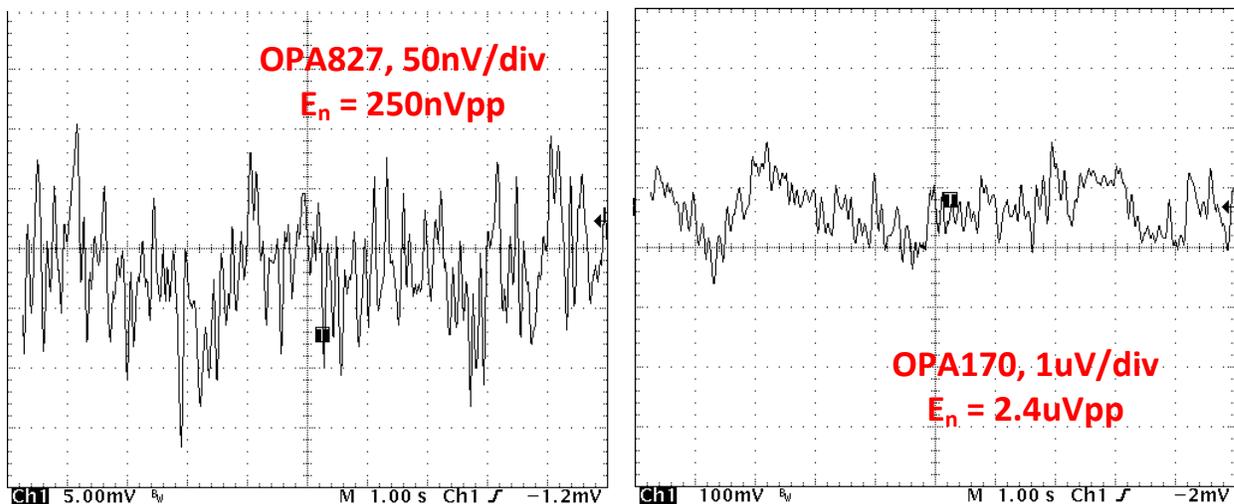


Figure 24: Measured 0.1Hz to 10Hz noise for OPA827 and OPA170

## 6.4 Measured Result Summary

Table 5 summarizes the measured results for the four example amplifiers tested using the filter board. The data sheet typical specification for 0.1Hz to 10Hz noise is given for comparison. In general the circuit performs well.

**Table 5: Data sheet specifications vs. measured results for five examples.**

Op amp	Data Sheet Noise spec	Measured
OPA827	250nVpp	250nVpp
OPA277	220nVpp	150nVpp
OPA170	2.0uVpp	2.4uVpp
OPA1652	1.5uVpp	1.5uVpp

## 7 Modifications

### 7.1 Selecting different amplifiers

The example shown in this design used the OPA827 in the filter stages. Other amplifiers that would be suitable for the filter are given in Table 6. Any amplifier can be tested as the DUT. The same fixture can be used for 5V amplifiers (e.g. OPA333). In the case of these type amplifiers use +/-2.5V supplies to avoid common mode limitations.

**Table 6: Brief Comparison of Amplifiers**

Amplifier	Max Supply Voltage (V)	Max Offset Voltage (uV)	Max Offset Drift (uV/C)	Bandwidth (MHz)	Bias Current (pA)
OPA827	36	150	2	22	10
OPA277	36	20	0.15	1	2800
OPA188	36	25	0.085	1	1400
OPA333	5.5	10	0.05	0.35	200
OPA335	5.5	5	0.05	2	200

### 7.2 Different DUT gain

The gain of the DUT was set to 1,000 to amplify noise so that it is measureable and also to insure that the first DUT is the dominant noise source. In some cases it may be useful to change the gain of the first stage.

## 8 About the Author

Arthur Kay is an applications engineering manager at TI where he specializes in the support of amplifiers, references, and mixed signal devices. Arthur focuses a good deal on industrial applications such as bridge sensor signal conditioning. Arthur has published a book and an article series on amplifier noise. Before working in applications engineering, he was a semiconductor test engineer for Burr-Brown and Northrop Grumman Corp. Arthur received his MSEE from Georgia Institute of Technology (1993), and BSEE from Cleveland State University (1992).

## 9 Acknowledgements & References

[1] Kay, A., *Operational Amplifier Noise*, Newnes, 2012, Chapter 5

[2] DIP Adapter EVM, Tool, Texas Instruments, <http://www.ti.com/tool/dip-adapter-evm>

[2] Filter Pro, Tool, Texas Instruments, <http://www.ti.com/tool/filterpro>

## Appendix A. Appendix

### A.1 Electrical Schematic and Bill of Materials

The electrical schematic and bill of materials for this design are shown in Figure A-1 and Figure A-2, respectively.

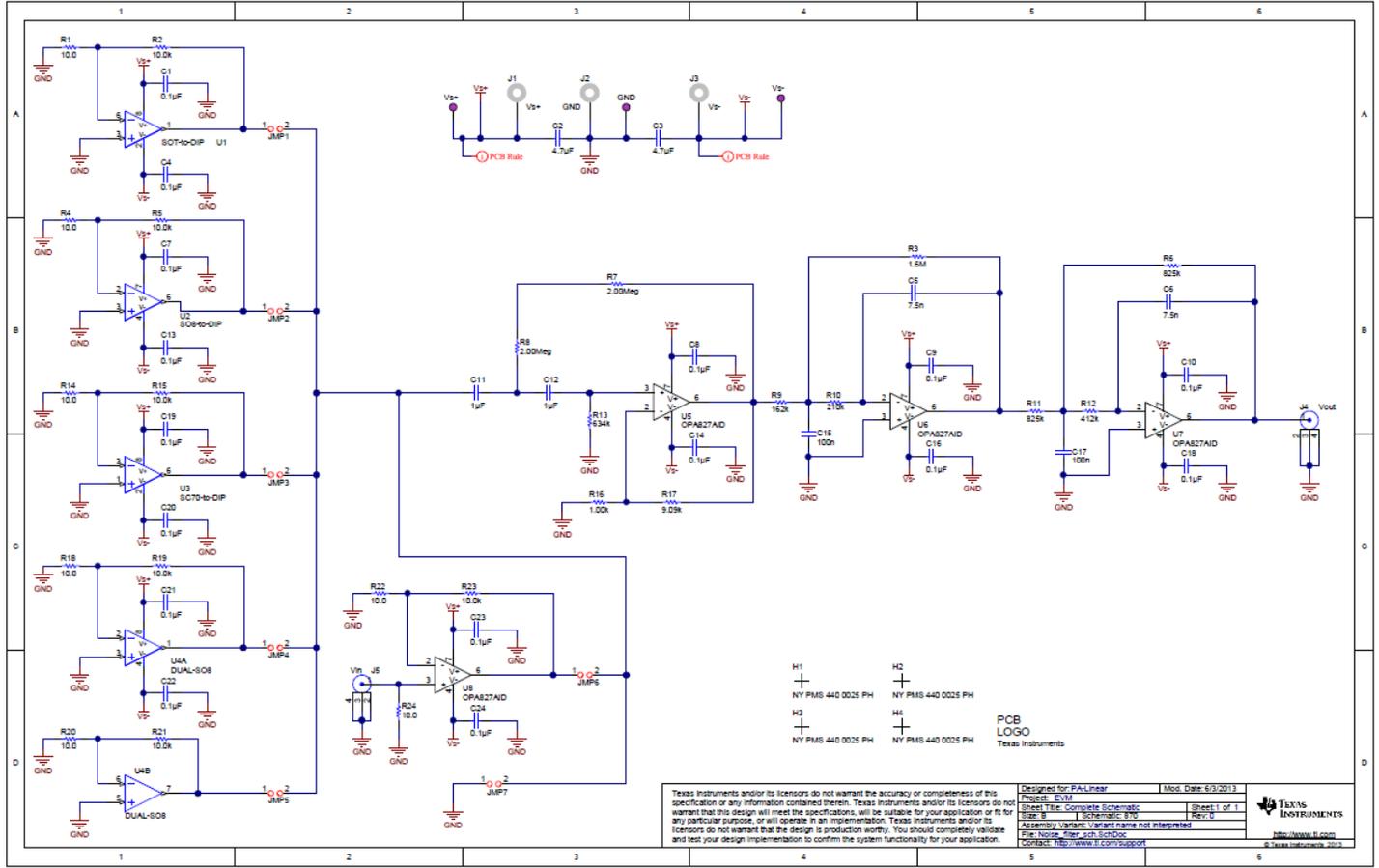


Figure A-1: Electrical Schematic

## A.2 Bill of Materials

Item	Qty	Value	Designator	Description	Manufacturer	Manufacturer Part No.	Supplier Part No.
1	14	0.1uF	C1, C4, C7, C8, C9, C10, C13, C14, C16, C18, C19, C20, C21, C22	CAP, CERM, 0.1uF, 50V, +/-5%, X7R, 0805	AVX	08055C104JAT2A	478-3352-1-ND
2	2	4.7uF	C2, C3	CAP, CERM, 4.7uF, 16V, +/-20%, X7R, 1206	TDK	C3216X7R1C475M160AB	445-5994-1-ND
3	2	7.5n	C5, C6	CAP CER 7500PF 50V 5% NPO 0805	TDK	GRM2195C1H752JA01D	490-1639-1-ND
4	2	1uF	C11, C12	CAP, CERM, 1uF, 50V, +/-10%, X7R, 0805	TDK	C2012X6S1H105K085AB	445-14501-1-ND
5	2	0.1uF	C15, C17	CAP CER 1UF 50V 10% X6S 0805	TDK	C2012X6S1H105K085AB	445-14501-1-ND
6	4		H1, H2, H3, H4	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	B&F Fastener	NY PMS 440 0025 PH	H542-ND
7	1	Vs+	J1	Standard Banana Jack, Uninsulated, 5.5mm	Keystone	575-4	575-4K-ND
8	1	GND	J2	Standard Banana Jack, Uninsulated, 5.5mm	Keystone	575-4	575-4K-ND
9	1	Vs-	J3	Standard Banana Jack, Uninsulated, 5.5mm	Keystone	575-4	575-4K-ND
10	2		J4, J5	CONN BNC JACK R/A 75 OHM PCB	TE Connectivity	1-1478032-0	A97560-ND
11	5		JMP1, JMP2, JMP3, JMP4, JMP5, JMP6, JMP7	CONN HEADER 50POS .100" SGL GOLD (cut as needed)	Samtec Inc	TSW-150-07-G-S	SAM1029-50-ND
12	5	10	R1, R4, R14, R18, R20	RES 10.0 OHM 1/10W 0.1% 0805	TE Connectivity	1-1614884-7	A103143CT-ND
13	5	10.0k	R2, R5, R15, R19, R21	RES 10K OHM 1/8W .1% 0805 SMD	Panasonic	ERA-6AEB103V	P10KDACT-ND
14	1	1.6M	R3	RES 1.6M OHM 1/10W 0.1% 0805	TE Connectivity	1-1614959-2	A103800CT-ND
15	2	825k	R6, R11	RES 825K OHM 1/8W 0.5% 0805 SMD	Panasonic	ERA-6AED8253V	P825KBNCT-ND
16	2	2.00Meg	R7, R8	RES, 2.00Meg ohm, 1%, 0.125W, 0805	Vishay-Dale	CRCW08052M00FKEA	541-2.00MCCT-ND
17	1	162k	R9	RES 162K OHM 1/8W .1% 0805 SMD	Vishay-Dale	ERA-6AEB1623V	P162KDACT-ND
18	1	210k	R10	RES 210K OHM 1/8W .1% 0805 SMD	Panasonic	ERA-6AEB2103V	P210KDACT-ND
19	1	412k	R12	RES 412K OHM 1/8W .1% 0805 SMD	Panasonic	ERA-6AEB4123V	P412KDACT-ND
20	1	634k	R13	RES 634K OHM 1/8W .1% 0805 SMD	Panasonic	ERA-6AEB6343V	P634KDACT-ND
21	1	1.00k	R16	RES, 1.00k ohm, 1%, 0.125W, 0805	Panasonic	ERA-6AEB102V	P1.0KDACT-ND
22	1	9.09k	R17	RES 9.09K OHM 1/8W .1% 0805 SMD	Panasonic	ERA-6AEB9091V	P9.09KDACT-ND
23	0		R23	Optional for gain set, Do Not Populate for Gain=1			
24	1	0	R22	RES 0.0 OHM 1/8W JUMP 0805 SMD	Panasonic	ERJ-6GEY0R00V	P0.0ACT-ND
25	1	GND	TP1	Test Point, TH, Compact, Red	Keystone	5124	5005K-ND
26	1	Vs-	TP2	Test Point, TH, Compact, Red	Keystone	5124	5005K-ND
27	1	Vs+	TP3	Test Point, TH, Compact, Red	Keystone	5124	5005K-ND
28	3		U5, U6, U7, U8	IC OPAMP JFET 22MHZ SGL 8VSSOP	Texas Inst.	OPA827AID	296-24280-1-ND

Figure A-2: Bill of Materials

## IMPORTANT NOTICE FOR TI REFERENCE DESIGNS

Texas Instruments Incorporated ("TI") reference designs are solely intended to assist designers ("Buyers") who are developing systems that incorporate TI semiconductor products (also referred to herein as "components"). Buyer understands and agrees that Buyer remains responsible for using its independent analysis, evaluation and judgment in designing Buyer's systems and products.

TI reference designs have been created using standard laboratory conditions and engineering practices. **TI has not conducted any testing other than that specifically described in the published documentation for a particular reference design.** TI may make corrections, enhancements, improvements and other changes to its reference designs.

Buyers are authorized to use TI reference designs with the TI component(s) identified in each particular reference design and to modify the reference design in the development of their end products. HOWEVER, NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY THIRD PARTY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT, IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI REFERENCE DESIGNS ARE PROVIDED "AS IS". TI MAKES NO WARRANTIES OR REPRESENTATIONS WITH REGARD TO THE REFERENCE DESIGNS OR USE OF THE REFERENCE DESIGNS, EXPRESS, IMPLIED OR STATUTORY, INCLUDING ACCURACY OR COMPLETENESS. TI DISCLAIMS ANY WARRANTY OF TITLE AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, QUIET ENJOYMENT, QUIET POSSESSION, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS WITH REGARD TO TI REFERENCE DESIGNS OR USE THEREOF. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY BUYERS AGAINST ANY THIRD PARTY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON A COMBINATION OF COMPONENTS PROVIDED IN A TI REFERENCE DESIGN. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, SPECIAL, INCIDENTAL, CONSEQUENTIAL OR INDIRECT DAMAGES, HOWEVER CAUSED, ON ANY THEORY OF LIABILITY AND WHETHER OR NOT TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES, ARISING IN ANY WAY OUT OF TI REFERENCE DESIGNS OR BUYER'S USE OF TI REFERENCE DESIGNS.

TI reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques for TI components are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

Reproduction of significant portions of TI information in TI data books, data sheets or reference designs is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards that anticipate dangerous failures, monitor failures and their consequences, lessen the likelihood of dangerous failures and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in Buyer's safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed an agreement specifically governing such use.

Only those TI components that TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components that have **not** been so designated is solely at Buyer's risk, and Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.